# MSKSEMI 美森科













**ESD** 

TVS

TSS

MOV

GDT

PLED

# TLV333IDBVR-MS/TLV2333IDR-MS

**Product specification** 





#### **GENERAL DESCRIPTION**

The TLVx333 series of CMOS operational amplifiers use a proprietary auto-calibration technique to simultan eously provide very low offset voltage ( $\pm4$ uV,maximum)and near-zero drift over time and temperature. These miniature,high-precision,low quiescent current (13.5uA)amplifiers offer high impedance inputs that have a com mon-mode range 100 mV beyond the rails,and rail-to-rail output that swings within 50 mV of the rails. Single or dual supplies as low as 1.8 V( $\pm0.9$  V)and up to 5.5 V( $\pm0.75$  V)can be used. These devices are optimized for low voltage, single-supply operation.

The TLV333IDBVR-MS(single version)is available in the 5-pin SOT23, while the TLV2333IDR-MS(dual version) available in the 8-pin SOIC and packages. All versions are specified for operation from -25° $\mathbb C$  to 125° $\mathbb C$ .

#### **FEATURES**

Input Offset Voltage:±1µV(Typ)

Zero Drift:0.01µV/℃(Typ)

• 0.01Hz-10Hz Noise:1.5µVpp

Quiescent Current:13.5µA

High Open-Loop Gain:150dB

Single or Dual Supply Operation

Supply Voltage: 1.8V to 5.5V

Rail-to-Rail Input/Output

Micro Size Packages:

TLV333IDBVR-MS:SOT-23-5

TLV2333IDR-MS:SOP-8

#### **TYPICALAPPLICATIONS**

- Temperature Sensors
- Active Filtering
- Transducers
- Electronic Scales
- Temperature Measurements
- Medical Instrumentation
- Battery-Powered Instruments
- Handheld Test Equipment

#### PACKAGE/ORDER INFORMATION

Part Number	Op Temp(℃)	Pac	kage	Pin Configuration	Marking	QTY
TLV333IDBVR-MS	-25°C~125˚C	SOT23-5		OUT 1 5 V+ V- 2 + IN 3 4 - IN	12 <u>YD</u>	3000
TLV2333IDR-MS	-25°C~125℃	SOP8		OUTA 1 8 V+ -INA 2 7 OUTB +INA 3 6 -INB V- 4 5 +INB	MSKSEMI TLV2333 MS XXX	2500



# **Pin Description**

	PIN	I/O	
NAME	SOT-23-5	1/0	DESCRIPTION
+IN	3	I	Positive(noninverting)input
-IN	4	I	Negative (inverting)input
NC	-	-	No Connection
OUT	1	0	Output
V+	5	-	Positive (highest)power supply
V-	2	-	Negative (lowest)power supply

PI	V	I/O	DESCRIPTION
NAME	SOP-8	1,0	DESCRIPTION
+INA	3	I	Noninverting input,channel A
+INB	5	ı	Noninverting input,channel B
-INA	2	I	Inverting input,channel A
-INB	6	ı	Inverting input,channel B
OUTA	1	0	Output,channel A
OUTB	7	0	Output,channel B
V-	4	-	Negative (lowest)power supply
V+	8	_	Positive(highest)power supply

# **Functional Block Diagram**

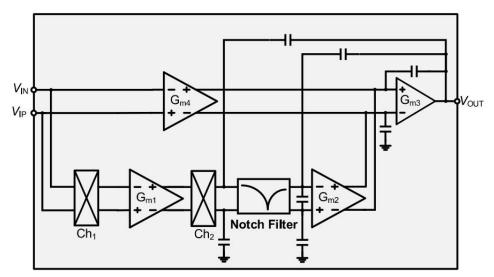


Figure 1. Typical Application



#### **SPECIFICATIONS**

# **Absolute Maximum Ratings**(1)

	MIN	MAX	UNIT
Supply Voltage		7	V
Signal Input Terminals Voltage (2)	- 0.3	(V+) + 0.3	V
Signal Input Terminals Current (2)	-1	1	mA
Output Short-Circuit <sup>(3)</sup>	Conti	mA	
Junction Temperature, T <sub>J</sub>		150	°C
Operating Temperature Range, T <sub>A</sub>	-25	150	°C
Storage Temperature Range, Tstg	-35	150	°C

- (1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Input terminals are diode clamped to the power-supply rails. Input signals that can swing more than 0.3V beyond the supply rails should be current limited to 10mA or less.
- (3) Short-circuit to ground, one amplifier per package.

## **ESD Ratings**

			VALUE	UNIT
	Clastrostatio disabares	Human body model (HBM)	±4000	V
V <sub>(ESD)</sub> Electrostatic discharge		Charged-device model (CDM)	±1000	V

# **Recommended Operating Conditions**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Supply Voltage Va	Single-supply	1.8	5.5	V
Supply Voltage, V <sub>S</sub>	Dual-supply	±0.9	±2.75	V
Specified temperature		<del>-</del> 25	125	°C



## **ELECTRICAL CHARACTERISTICS**

At  $T_A = 25$ °C,  $V_S = \pm 2.5$ V,  $V_{IN}=0$ V, unless otherwise noted.

PARAMETER		CONDITIONS	MIN	TYP	MAX	UNIT
OFFSET V	OFFSET VOLTAGE					
Vos	Input Offset Voltage			±1	±10	μV
dV <sub>OS</sub> /dT	Input Offset Voltage Average Drift	T <sub>A</sub> = <b>-</b> 25°C to 125°C		0.01		μV/°C
INPUT CL	JRRENT					
				1	20	рА
<b>I</b> B	Input Bias Current	T <sub>A</sub> = -25°C to 125°C			180	рА
los	Input Offset Current			1	20	рА
NOISE						
V <sub>N</sub>	Input Voltage Noise	f=0.1Hz to 10Hz		1.5	2	μV <sub>PP</sub>
	Input Voltage Noise PSD	f=1kHz		79.4		nV/√Hz
INPUT VO	DLTAGE					
V <sub>CM</sub>	Common-Mode Voltage Range		(VS-)- 0.1		(VS+)+0.1	V
CMRR	Common-Mode Rejection Ratio	ΔV <sub>IN</sub> =1V	130	135		dB
GAIN						
A <sub>V</sub>	Open-Loop Voltage Gain	ΔV <sub>OUT</sub> =1V	140	150		dB
FREQUE	NCY RESPONSE					
GBW	Gain-Bandwidth Product			550		kHz
SR	Slew Rate	G = +1 , V <sub>IN</sub> =4V Step		0.1		V/us
OUTPUT						
V <sub>OUT</sub> -	Output Swing from Rail			0.32	0.5	mV
I <sub>sc</sub>	Output Short-Circuit Current			21		mA
C <sub>L</sub> <sup>(1)</sup>	Capacitive Load Drive	G = +1 , V <sub>IN</sub> =4V Step			1	nF
POWER S	SUPPLY					
PSRR	Power-Supply Rejection Ratio	ΔV <sub>S</sub> =1V		135		dB



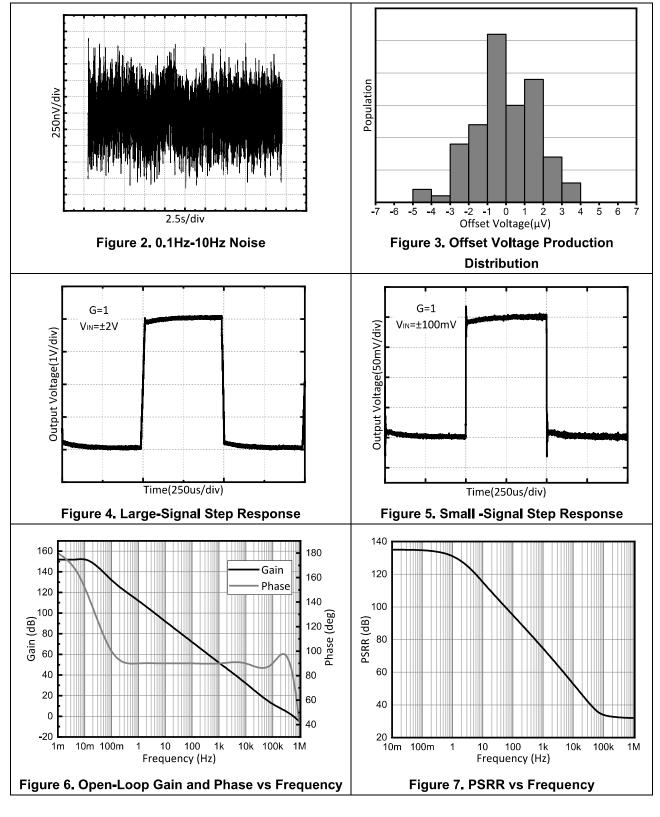
Vs	Operating Voltage Range	I <sub>O</sub> =0A	1.8		5.5	V
	. Quiescent	TLV333IDBVR-MS		13.5		uA
IQ	Current/Amplifier	TLV2333IDR-MS		25		uA

<sup>(1)</sup> Capacitive load drive means that above a given maximum value, the output waveform will oscillate under the step response

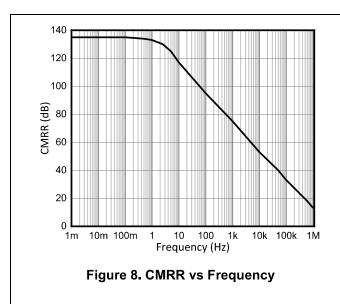


#### TYPICAL CHARACTERISTICS

At TA = 25°C,  $V_S = \pm 2.5V$ ,  $V_{IN}=0V$ , unless otherwise noted.







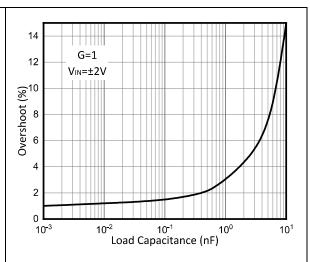


Figure 9. Large-Signal Overshoot vs Load Capacitance

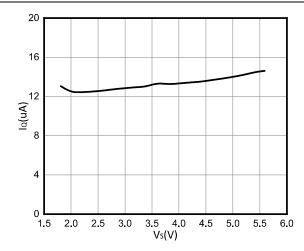


Figure 10. Quiescent Current vs Supply Voltage

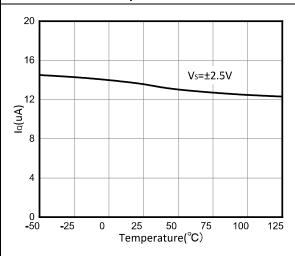


Figure 11. Quiescent Current vs Temperature

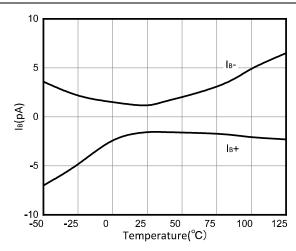


Figure 12. Input Bias Current vs Temperature

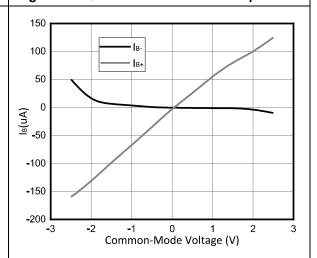


Figure 13. Input Bias Current vs Common-Mode Voltage



# **Detailed Description**

#### Overview

The TLVx333 is a family of Zero-Drift,low-power,rail-to-rail input and output operational amplifiers. These devices operate from 1.8 V to 5.5 V, are unity-gainstable, and are suitable for a wide range of general-purpose applications. The Zero-Drift architecture provides ultra low offset voltage and near-zero offset voltage drift.

#### **Functional Block Diagram**

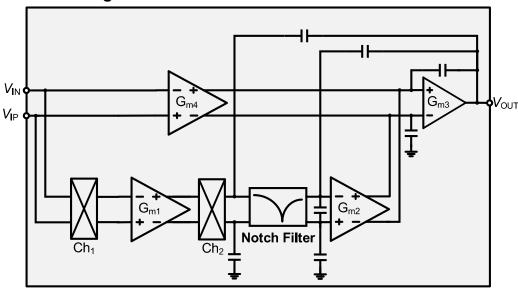


Figure 14. TLVx333 Functional Block Diagram

#### **Feature Description**

The TLVx333 are unity-gainstable and free from unexpected output phase reversal. These devices use a proprietary auto-calibration technique to provide low offset voltage and very low drift over time and temperature. For lowest offset voltage and precision performance, optimize circuit layout and mechanical conditions. Avoid temperature gradients that create thermoelectric (Seebeck) effects in the thermocouple junctions formed from connecting dissimilar conductors. Cancel these thermally- generated potentials by assuring they are equal on both input terminals. Other layout and design

#### considerations include:

- Use low thermoelectric-coefficient conditions (avoid dissimilar metals).
- Thermally isolate components from power supplies or other heat sources.
- Shield operational amplifier and input circuitry from air currents, such as cooling fans.

Following these guidelines reduces the likelihood of junctions being at different temperatures, which can cause thermoelectric voltages of 0.1  $\mu$ V/C or higher, depending on materials used.

#### Input Voltage

The TLVx333 input common-mode voltage range extends 0.1 V beyond the supply rails. The TLVx333 is designed to cover the full range without the troublesome transition region found in some other rail-to-rail amplifiers.

#### **Device Functional Modes**

The TLVx333 device has a single functional mode. The device is powered on as long as the power supply voltage is between 1.8V(±0.9 V)and 5.5V (±2.75 V).



# **Application and Implementation**

#### **Application Information**

The TLVx333 family is a unity-gain stable, precision operational amplifier with very low offset voltage drift; these devices are also free from output phase reversal. Applications with noisy or high-impedance power supplies require decoupling capacitors close to the device power-supply pins. In most cases,  $0.1-\mu F$  capacitors are adequate.

# **Typical Applications**

#### 1 Voltage Follower

As shown in Figure 15, the voltage gain is 1. With this circuit, the output voltage  $V_{OUT}$  is configured to be equal to the input voltage  $V_{IN}$ . Due to the high input impedance and low output impedance, the circuit can also stabilize the output voltage, the output voltage expression is

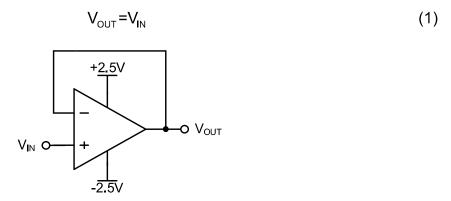


Figure 15. Voltage Follower

#### 2 Inverting Proportional Amplifier

As shown in Figure 16, for a reverse-phase proportional amplifier, the input voltage  $V_{IN}$  is amplified by a voltage gain that depends on the ratio of R1 to R2. The output voltage  $V_{OUT}$  is inversely with the input voltage  $V_{IN}$ . The input impedance of the circuit is equal to R1, and the output voltage expression is

$$V_{\text{OUT}} = -\frac{R2}{R1}V_{\text{IN}}$$

$$V_{\text{IN}} = -\frac{R2}{R1}V_{\text{IN}}$$

$$V_{\text{IN}} = -\frac{R2}{R1}V_{\text{IN}}$$

$$V_{\text{OUT}} = -\frac{R2}{R1}V_{\text{IN}}$$

Figure 16. Inverting Proportional Amplifier



#### 3 Noninverting Proportional Amplifier

As shown in Figure 17, for a noninverting amplifier, the input voltage  $V_{IN}$  is amplified by a voltage gain that depends on the ratio of R1 to R2. The output voltage  $V_{OUT}$  is in phase with the input voltage  $V_{IN}$ . In fact, this circuit has a high input impedance because its input side is the same as the input side of the operational amplifier. The output voltage expression is

$$V_{OUT} = (1 + \frac{R2}{R1})V_{IN}$$
 (3)

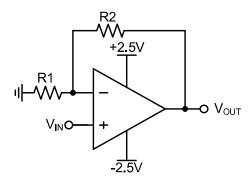
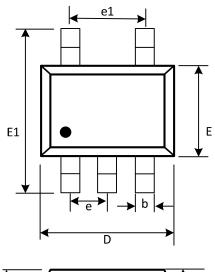


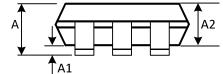
Figure 17. Noninverting Proportional Amplifier

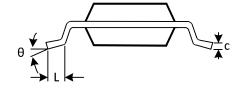


# **PACKAGE DESCRIPTION**

# SOT23-5





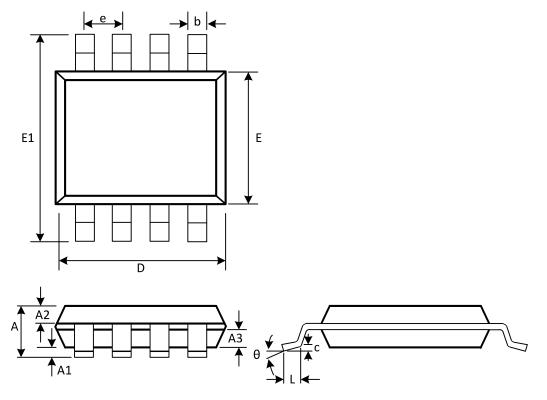


(Unit: mm)

Symbol	Min	Max		
А	1.05	1.25		
A1	0	0.1		
A2	1.05	1.15		
b	0.3	0.5		
С	0.1	0.2		
D	2.82	3.02		
e	0.95(	(BSC)		
e1	1.9(E	BSC)		
E	1.5	1.7		
E1	2.65	2.95		
L	0.3	0.6		
θ	0°	8°		



# SOP-8



(Unit: mm)

Symbol	Min	Max
А	1.300	1.600
A1	0.050	0.200
A2	0.550	0.650
A3	0.550	0.650
b	0.356	0.456
С	0.203	0.233
D	4.800	5.000
е	1.270	(BSC)
Е	3.800	4.000
E1	5.800	6.200
L	0.400	0.800
θ	0°	8°



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